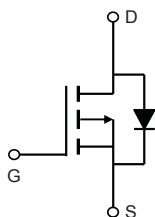


J7116DFN

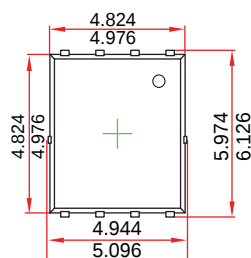
P-Channel MOSFET

Features

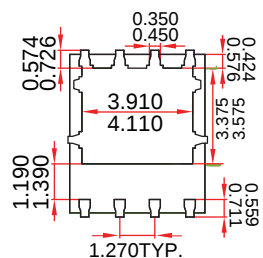
- V_{DS} -30V
- I_D -75A
- $R_{DS(ON)}$ (at $V_{GS} = -10V$) = 5.3m Ω (Typ.)
- $R_{DS(ON)}$ (at $V_{GS} = -4.5V$) = 8.4m Ω (Typ.)



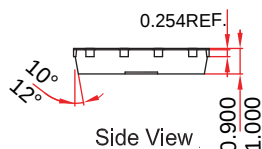
DFN5*6-8



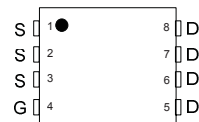
Top View



Bottom View



Side View



Dimensions in millimeter

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted.)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current $T_C=25^\circ\text{C}$	I_D	-75	A
Pulsed Drain Current $T_C=25^\circ\text{C}$	I_{DM}	-300	
Single Pulsed Avalanche Energy (Note 1)	EAS	122	mJ
Power Dissipation $T_C=25^\circ\text{C}$	P_D	45	W
Power Dissipation $T_A=25^\circ\text{C}$		4.2	
Thermal Resistance, Junction- to-Ambient (Note 2)	$R_{\theta JA}$	30	$^\circ\text{C/W}$
Thermal Resistance, Junction- to-Case (Note 2)	$R_{\theta JC}$	2.8	
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 to 150	
Lead Temperature for Soldering Purposes (1/8" from case for 10s)	T_L	260	

Notes 1. EAS condition: $L=0.5\text{mH}$, $R_G=25\Omega$, $I_{AS} = -20A$, $V_{GS} = -10V$. Starting $T_J = 25^\circ\text{C}$

2. Mounted on a glass epoxy board of 50 mm x 50 mm x 0.8 mm

■ Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	I _D = -250μA, V _{GS} = 0V	-30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -30V, V _{GS} = 0V			-1	μA
Gate-Body Leakage Current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V			± 100	nA
On characteristics (note1)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-1.0		-2.0	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D = -20A		5.3	8	mΩ
		V _{GS} = -4.5V, I _D = -20A		8.4	13	
Dynamic characteristics (note 2)						
Input Capacitance	C _{iss}	V _{GS} =0V, V _{DS} = -15V, f = 1MHz		3770		pF
Output Capacitance	C _{oss}			545		
Reverse Transfer Capacitance	C _{rss}			395		
Switching characteristics (note 2)						
Total Gate Charge	Q _g	V _{DS} = -15V, I _D = -20A V _{GS} = -10V		65		nC
Gate Source Charge	Q _{gs}			16.1		
Gate Drain Charge	Q _{gd}			18.1		
Turn-On DelayTime	t _{d(on)}	V _{DD} =-15V,I _D =-20A, V _{GS} =-10V,R _G =3Ω		14.4		ns
Turn-On Rise Time	t _r			11.2		
Turn-Off DelayTime	t _{d(off)}			99.5		
Turn-Off Fall Time	t _f			47.5		
Drain-Source Diode Characteristics						
Reverse Recovery Time	t _{rr}	T _j =25℃,I _{sd} =-20A, V _{GS} =0V di/dt=-100A/μs		37		nS
Reverse Recovery Charge	Q _{rr}			35		nC
Diode Forward Voltage	V _{SD}	I _S = -20 A,V _{GS} = 0V		-0.8	-1.2	V

Notes 1. Pulse Test : Pulse Width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

2. Guaranteed by design, not subject to production.

Typical Characteristics

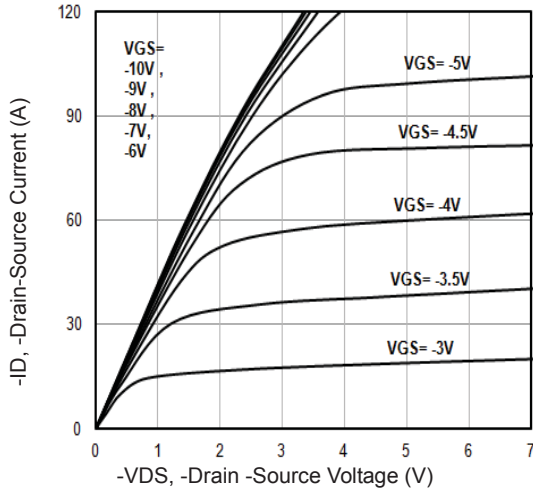


Fig1. Typical Output Characteristics

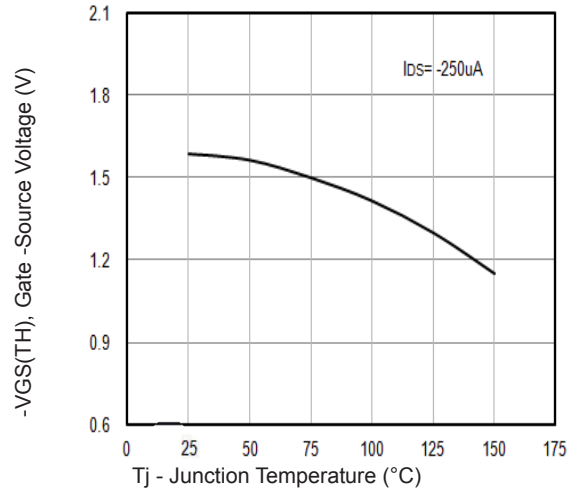


Fig2. $-V_{GS(TH)}$ Gate -Source Voltage Vs. T_J

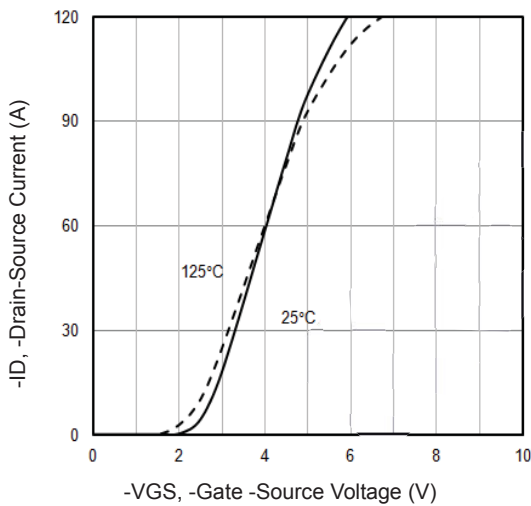


Fig3. Typical Transfer Characteristics

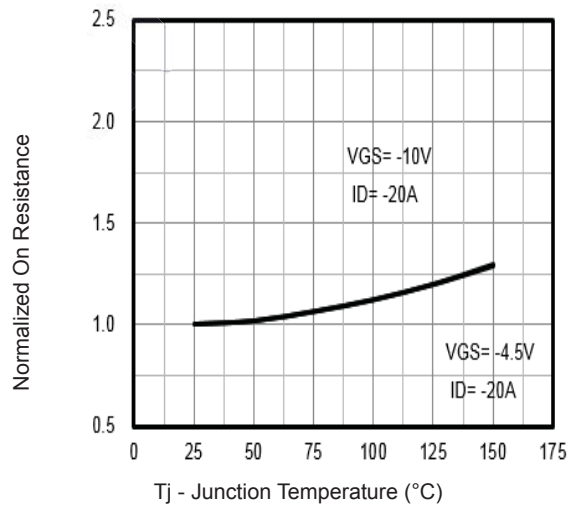


Fig4. Normalized On-Resistance Vs. T_J

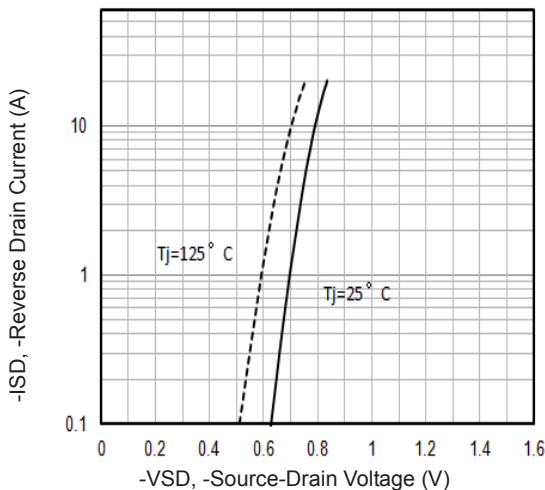


Fig5. Typical Source-Drain Diode Forward Voltage

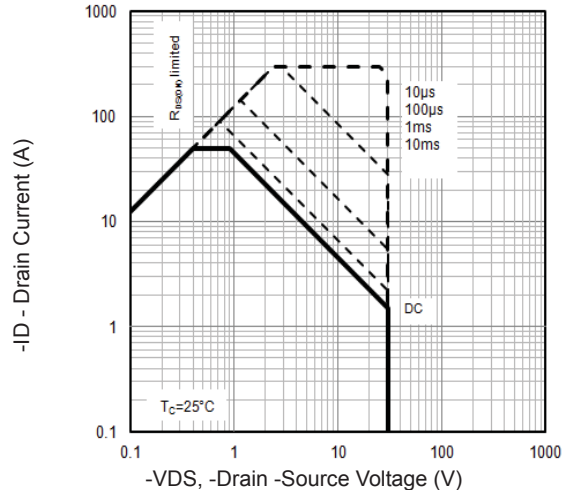


Fig6. Maximum Safe Operating Area

Typical Characteristics

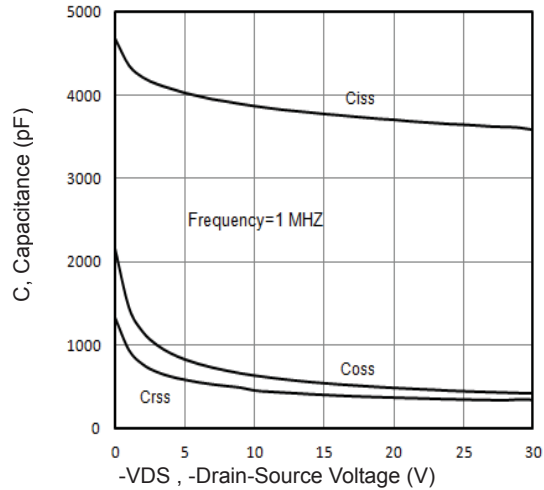


Fig7. Typical Capacitance Vs. Drain-Source Voltage

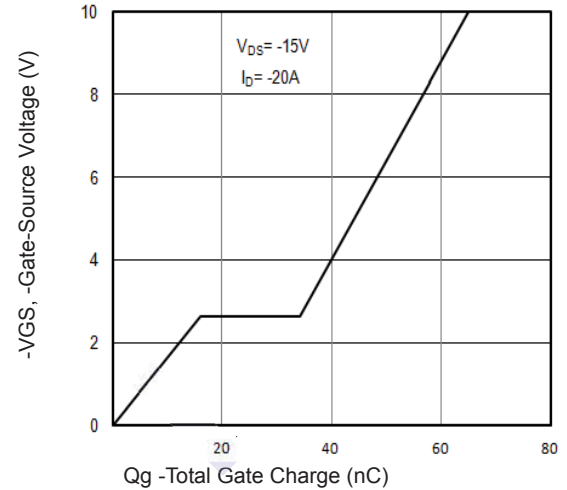


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

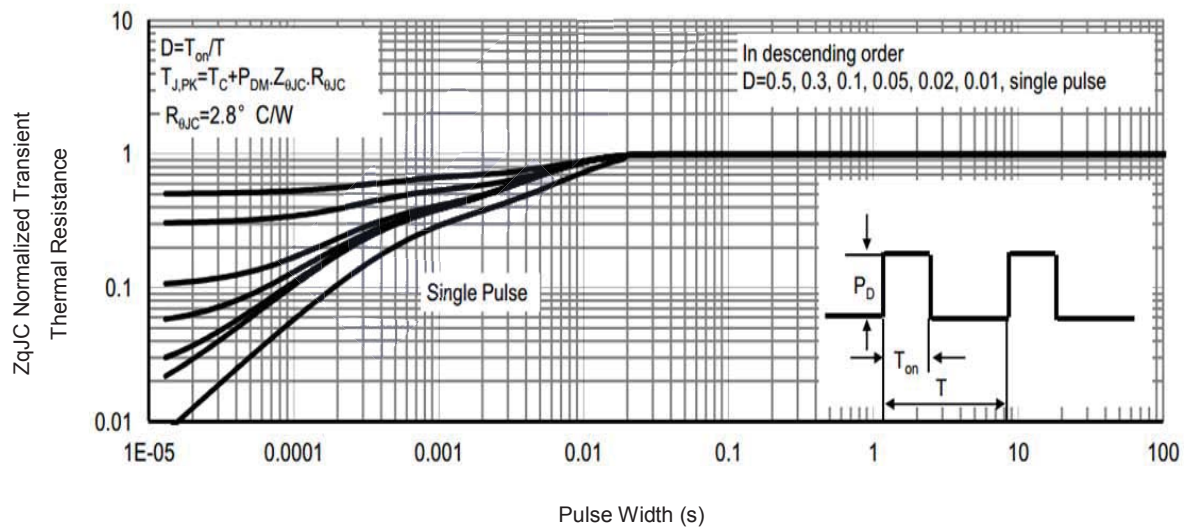


Fig9. Normalized Maximum Transient Thermal Impedance

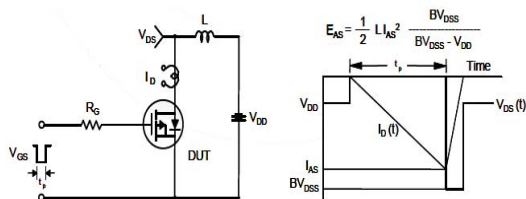


Fig10. Unclamped Inductive Test Circuit and Waveforms

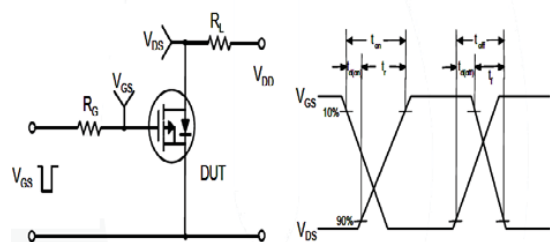


Fig11. Switching Time Test Circuit and waveforms